

[0279] The spin-valve type thin-film device shown in FIG. 11 includes an antiferromagnetic layer 80 which has a long portion extending on and along a substrate 10 in the X direction as shown. The antiferromagnetic layer 80 is projected upward in a central portion thereof. Laminated on the projected portion of the antiferromagnetic layer 80 are a first pinned magnetic layer 81, a nonmagnetic material layer 82, a second pinned magnetic layer 83, a nonmagnetic electrically conductive layer 84, a first free magnetic layer 85, a nonmagnetic material layer 86, a second free magnetic layer 87, and a protective layer 15. The laminate, composed of the layers from the substrate 10 through the protective layer 15, forms a multilayer film 201.

[0280] In accordance with the present invention, the antiferromagnetic layer 80 is made of a Pt—Mn (platinum-manganese) alloy. Instead of the Pt—Mn alloy, the antiferromagnetic layer 80 may be made of an X—Mn alloy where X is a material selected from the group consisting of Pd, Ir, Rh, Ru, and alloys thereof, or a Pt—Mn—X' alloy where X' is a material selected from the group consisting of Pd, Ir, Rh, Ru, Au, Ag, and alloys thereof.

[0281] The first pinned magnetic layer 81, the second pinned magnetic layer 83, the first free magnetic layer 85, and second free magnetic layer 87 are made of an Ni—Fe (nickel-iron) alloy, Co (cobalt), an Fe—Co (iron-cobalt) alloy, or an Fe—Co—Ni alloy.

[0282] The nonmagnetic electrically conductive layer 84 is made of a low electrical-resistance nonmagnetic electrically conductive material such as Cu (copper).

[0283] Referring to FIG. 11, metallic layers 88 and 88, made of Cr or the like, and functioning as a buffer layer or an alignment layer, extend from a horizontal portion thereof coextending a width dimension T44 of the antiferromagnetic layer 80 in the X direction, rising along the side end faces of the first pinned magnetic layer 81, the nonmagnetic material layer 82, the second pinned magnetic layer 83, the nonmagnetic electrically conductive layer 84, and the first free magnetic layer 85. The use of the metallic layers 88 and 88 helps increase the strength of the bias magnetic field created by hard bias layers 89 and 89 to be described later.

[0284] Deposited on top of the metallic layers 88 and 88 are the hard bias layers 89 and 89 which are made of a Co—Pt (cobalt-platinum) alloy or a Co—Cr—Pt (cobalt-chromium-platinum) alloy.

[0285] Intermediate layers 90 and 90, made of a nonmagnetic material, such as Ta, are respectively deposited on the hard bias layers 89 and 89. Electrode layers 91 and 91, made of Cr, Au, Ta, or W, are respectively deposited on top of the intermediate layers 90 and 90.

[0286] Since the antiferromagnetic layer 80 extends beneath and along the hard bias layers 89 and 89 as shown in FIG. 11, the thickness of the hard bias layers 89 and 89 can be made thinner. The hard bias layers 89 and 89 are thus easily produced using a sputtering technique.

[0287] Referring to FIG. 11, the first pinned magnetic layer 81 and the second pinned magnetic layer 83, having different magnetic moments, are laminated to each other with the nonmagnetic material layer 82 interposed therebetween, and function as a single pinned magnetic layer P.

[0288] The first pinned magnetic layer 81 is deposited on and in contact with the antiferromagnetic layer 80, and is subjected to annealing in the presence of a magnetic field. An exchange anisotropic magnetic field takes place through exchange coupling at the interface between the first pinned magnetic layer 81 and the antiferromagnetic layer 80. The magnetization direction of the first pinned magnetic layer 81 is thus pinned in the Y direction. When the magnetization direction of the first pinned magnetic layer 81 is pinned in the Y direction, the magnetization direction of the second pinned magnetic layer 83, separated from the first pinned magnetic layer 81 by the intervening nonmagnetic material layer 82, is pinned to be antiparallel to the magnetization direction of the first pinned magnetic layer 81.

[0289] The direction of the sum of the magnetic moments of the first pinned magnetic layer 81 and the second pinned magnetic layer 83 becomes the magnetization direction of the pinned magnetic layer P.

[0290] The first pinned magnetic layer 81 and the second pinned magnetic layer 83 are in a ferrimagnetic state with magnetization directions thereof being antiparallel, and the magnetization direction of the first pinned magnetic layer 81 and the magnetization direction of the second pinned magnetic layer 83 mutually pin each other. The magnetization direction of the pinned magnetic layer P, as a whole, is advantageously stabilized in one direction.

[0291] Referring to FIG. 11, the first pinned magnetic layer 81 and the second pinned magnetic layer 83 are manufactured of the same material with thicknesses thereof made different so that the two layers have different magnetic moments.

[0292] The nonmagnetic material layer 82, interposed between the first pinned magnetic layer 81 and the second pinned magnetic layer 83, is preferably made of a material selected from the group consisting of Ru, Rh, Ir, Cr, Re, Cu, and alloys thereof.

[0293] The first free magnetic layer 85 and the second free magnetic layer 87 are formed to have different magnetic moments. Here again, the first free magnetic layer 85 and the second free magnetic layer 87 are manufactured of the same material with thicknesses thereof made different so that the two layers have different magnetic moments.

[0294] The nonmagnetic material layer 86 is preferably made of a material selected from the group consisting of Ru, Rh, Ir, Cr, Re, Cu, and alloys thereof.

[0295] Referring to FIG. 11, the first free magnetic layer 85 and the second free magnetic layer 87, having different magnetic moments, are laminated with the nonmagnetic material layer 86 interposed therebetween, and function as a single free magnetic layer F.

[0296] The first free magnetic layer 85 and the second free magnetic layer 87, which are in a ferrimagnetic state with magnetization directions thereof being antiparallel, namely different from each other by 180 degrees, achieve the same effect, which can be provided by the use of a thin free magnetic layer F. This arrangement reduces the saturation magnetization, causing the magnetization of the free magnetic layer F to easily vary, and thereby improving the magnetic field detection sensitivity of the magnetoresistive-effect device.